



NPN PRE-BIASED SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features

- Epitaxial Planar Die Construction
- Built-In Biasing Resistors, R₁ Only
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

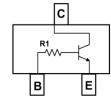
R ₁ (NOM)	
4.7kΩ	

SOT23

Top View

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208⁽²⁾
- Weight: 0.008 grams (Approximate)



Device Schematic – Top View

Ordering Information (Note 5)

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
ADTC143TCAQ-7	Automotive	1Z6	7	8	3,000
ADTC143TCAQ-13	Automotive	1Z6	13	8	10,000

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

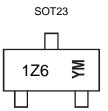
 See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/product-compliance-definitions/.

5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



1Z6 = Product Type Marking Code (See Table above) YM = Date Code Marking Y = Year (ex: E = 2017) M = Month (ex: 9 = September)

Date Code Key

Year	2017	2018	2019	2020	202	1 20)22	2023	2024	2025	2026	2027
Code	E	F	G	Н			J	К	L	М	Ν	0
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	50	V
Collector-Emitter Voltage	V _{CEO}	50	V
Emitter-Base Voltage	V _{EBO}	5	V
Collector Current	I _C (Max)	100	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	PD	310	mW
Thermal Resistance, Junction to Ambient Air (Note 6)	R _{0JA}	403	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Note: 6. Mounted on FR-4 PC Board with minimum recommended pad layout.



150

100

50

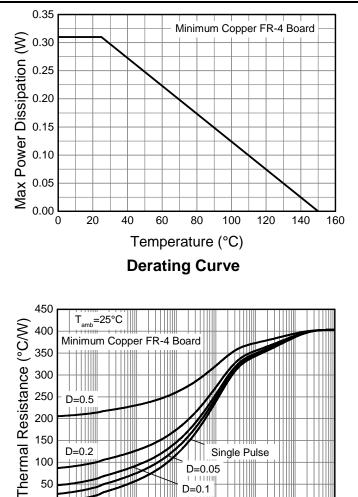
0

100µ

D=0.2

1m

Thermal Characteristics and Derating Information



Single Pulse

10

100

1k

D=0.05

1

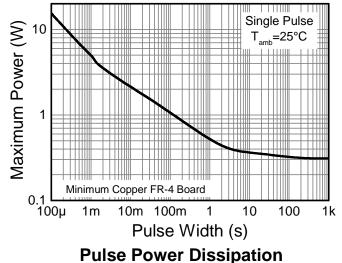
D=0.1

Pulse Width (s)

Transient Thermal Impedance

100m

10m





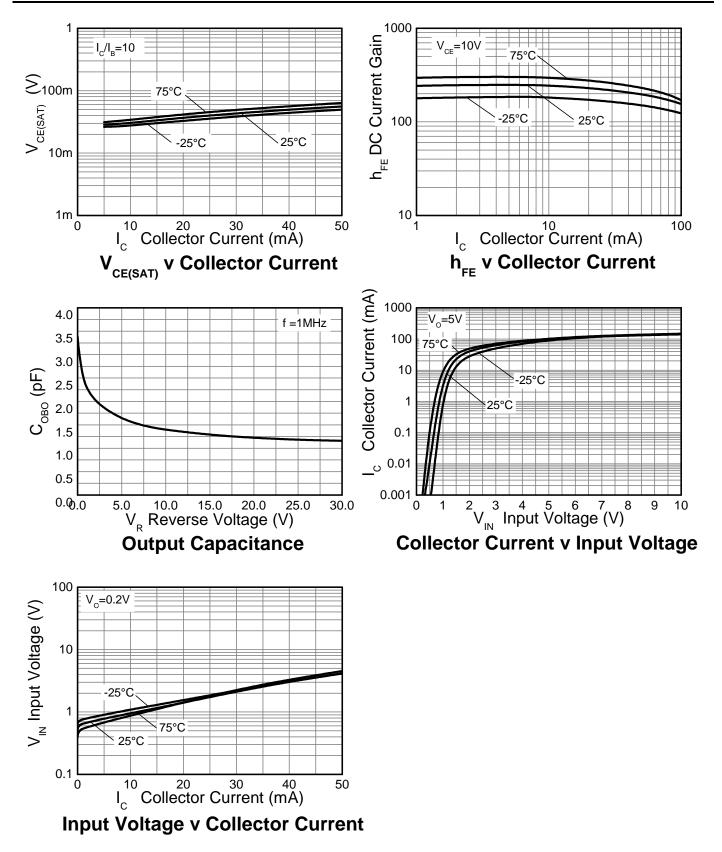
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	50	—	—	V	$I_{\rm C} = 50\mu A$
Collector-Emitter Breakdown Voltage	BV _{CEO}	50	—	_	V	I _C = 1mA
Emitter-Base Breakdown Voltage	BV _{EBO}	5	_		V	I _E = 50μA
Collector Cutoff Current	I _{CBO}	—	—	0.5	μA	$V_{CB} = 50V$
Emitter Cutoff Current	I _{EBO}	—	—	0.5	μA	$V_{EB} = 4V$
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	_	0.3	V	$I_{C}/I_{B} = 2.5 \text{mA}/0.25 \text{mA}$
DC Current Transfer Ratio	h _{FE}	100 120	250 —	600 630	_	$I_C = 1mA$, $V_{CE} = 5V$ $I_C = 5mA$, $V_{CE} = 5V$
Input Resistor (R1) Tolerance	ΔR_1	-30		+30	%	—
Gain-Bandwidth Product (Note 7)	fT	_	250	_	MHz	V _{CE} = 10V, I _E = 5mA, f = 100MHz

Note: 7. Transistor - For Reference Only.



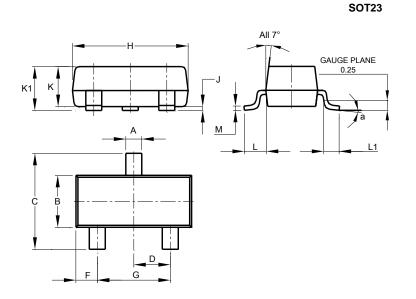
Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)





Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

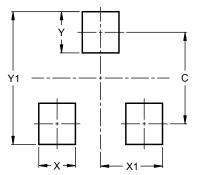


SOT23						
Dim	Min	Max	Тур			
Α	0.37	0.51	0.40			
В	1.20	1.40	1.30			
С	2.30	2.50	2.40			
D	0.89	1.03	0.915			
F	0.45	0.60	0.535			
G	1.78	2.05	1.83			
Н	2.80	3.00	2.90			
J	0.013	0.10	0.05			
ĸ	0.890	1.00	0.975			
K1	0.903	1.10	1.025			
L	0.45	0.61	0.55			
L1	0.25	0.55	0.40			
М	0.085	0.150	0.110			
а	0°	8°				
All	Dimens	ions in	mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.





Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Y	0.9
Y1	2.9



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